

Appl. No. 10/593,602
Amdt. dated May 21, 2009
Reply to Office Action of April 24, 2009
Attorney Docket No. 1217-062719

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/593,602 Confirmation No. 2582
Applicant : Hiroki YOKOYAMA
Filed : September 21, 2006
Title : Substrate for Device Bonding and Method for Manufacturing Same
Art Unit : 2815
Examiner : Jasmine Jhihan B. Clark
Customer No. : 28289

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

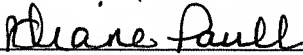
AMENDMENT

Sir:

In response to the Office Action of April 24, 2009, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.

I hereby certify that this correspondence is being electronically submitted to the United States Patent and Trademark Office on the date set forth below.	
Diane Paul	
(Name of Person Mailing Paper)	
	05/21/2009
Signature	Date